



## News Release

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FOR IMMEDIATE RELEASE

### **SUMIT™ Interface Grows to 6 PCI Express x1 lanes**

*Embedded interface upgraded with more PCIe x1, USB 2.0 and LPC capabilities*

San Jose, CA, March 30, 2009 - The Small Form Factor Special Interest Group (SFF-SIG), a collaboration of suppliers of embedded component, board and system technologies, announced today an update to the SUMIT Interface Standard. Revision 1.3 provides additional capability for embedded computing by supporting four additional PCIe x1 lanes for a total of six, one additional USB 2.0 interface for a total of four, and DMA support on the LPC bus to enable higher-speed data transfers. The updates to the Specification are fully upward compatible and do not obsolete or render any existing design incompatible or out of date. The SUMIT Interface now supports the following:

- Six PCIe x1 Lanes *OR* two PCIe x1 Lane and one PCIe x4 Lane
- Four USB 2.0 interfaces
- ExpressCard
- Low Pin Count Bus (LPC)
- SPI.uWire
- SMBus/I<sup>2</sup>C Bus

“We expanded the SUMIT Interface with an option for four more PCI Express x1 lanes in order to meet the I/O needs of future applications,” Paul Rosenfeld, SFF-SIG President. “The original Specification was sufficient for roughly 80% of embedded applications using PCI Express. Building on SUMIT’s initial success, we wanted to provide additional capability to make SUMIT attractive for a wide variety of different embedded board form-factors in the future. As new

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chipsets and I/O hubs from the semiconductor companies add PCIe x1 lanes the SUMIT Interface will have support already built-in”.

The SUMIT acronym stands for Stackable Unified Module Interconnect Technology™ and is pronounced “Sum it”. SUMIT is an electromechanical interface specification that enables all common serial and legacy chipset expansion buses for next generation products. It is a stackable, I/O-centric serial expansion technology that is independent of any particular board form factor. The purpose is to provide a compact, stackable, multi-board I/O expansion solution for future embedded systems designs which are suitable for industrial environments.

SUMIT was introduced by the SFF-SIG at the 2008 Embedded Systems Conference Silicon Valley. It targets the next-generation of low power, expandable single board computers and their I/O requirements. Companies interested in participating in the future evolution of the SUMIT, COMIT™, MiniBlade™ Specifications or other small form factor definitions should contact the SFF-SIG at [info@sff-sig.org](mailto:info@sff-sig.org).

### **About the Small Form Factor Special Interest Group**

The Small Form Factor Special Interest Group is an international organization devoted to identifying, creating, and promoting standards that help electronics system and device manufacturers and integrators move to small form factor technologies and building blocks in their products, and protect their investments. Benefits of small form factor products include smaller size, reduced power consumption (eco-friendly, “green” products), and greater reliability compared to larger legacy products.

The SIG’s philosophy is to embrace the latest technologies, as well as maintain legacy compatibility and enable smooth transition solutions to next-generation interfaces. For more information about the SFF SIG, please visit [www.sff-sig.org](http://www.sff-sig.org) or e-mail [info@sff-sig.org](mailto:info@sff-sig.org).

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